

REMARKS

This is in response to the Office Action dated April 10, 2006. Claims 1-13 are currently pending.

Formality Objections

The specification stands objected to in section 2 of the Office Action. This formality objection is respectfully traversed. For example and without limitation, example support for the “external connection terminal” in claim 1 and the “inner lead” in claim 7 may be found at pg. 30, last line, to pg. 31, second line, of the instant specification. The formality objection should thus be withdrawn.

Claim 6 stands rejected under 35 U.S.C. Section 112, second paragraph, as being allegedly indefinite. It is respectfully submitted that the changes to claim 6 herein address and overcome any potential issue in this respect.

Claim 1 stands rejected under 35 U.S.C. Section 102(b) as being allegedly anticipated by Wang. This Section 102(b) rejection is respectfully traversed for at least the following reasons.

Claim 1 as amended requires that “the second wiring layer includes a plurality of wirings *formed in the region under said bonding pad*, a predetermined wiring of said plurality of wirings is electrically connected to said bonding pad, and an insulating film is provided for insulating said bonding pad from other wirings than the predetermined wiring among said plurality of wirings *so that a plurality of wirings of the second wiring layer, which are located directly under the bonding pad, are insulated from the bonding pad by the insulating film*, wherein said insulating film is formed over said other wirings so as to directly contact the bonding pad.” For example and without limitation, Fig. 6 of the instant application illustrates that a plurality of wirings 12 of the second wiring layer that are insulated from the bonding pad 1 are formed in the

region under said bonding pad 1, and that a plurality of wirings 12 of the second wiring layer, which are located directly under the bonding pad 1, are insulated from the bonding pad 1 by the insulating film 5.

Wang fails to disclose or suggest the aforesaid italicized features of claim 1. In Fig. 3 of Wang, the only wiring 80 that is insulated from the bonding pad 100 is *not* formed *directly under* the bonding pad as called for in claim 1. Accordingly, the aforesaid italicized and quoted features of claim 1 are not present or suggested in Wang. The Section 102(b) rejection of claim 1 based on Wang is incorrect for at least this reason and should be withdrawn.

Claim 7 requires that the “second wiring layer includes a plurality of wirings formed in the region right under said bonding pad, a predetermined wiring of said plurality of wirings is connected to said bonding pad, and an insulating film is provided for insulating said bonding pad from other wirings than the predetermined wiring among said plurality of wirings so that a *plurality of wirings of the second wiring layer, which are located **directly under** the bonding pad, are insulated from the bonding pad by the insulating film*, and wherein said insulating film is formed over said other wirings so as to directly contact the bonding pad.” Wang fails to disclose or suggest these features of claim 7. In Fig. 3 of Wang, the only wiring 80 that is insulated from the bonding pad 100 is *not* formed *directly under* the bonding pad as called for in claim 7. Accordingly, the aforesaid italicized and quoted features of claim 7 are not present or suggested in Wang. The Section 102(b) rejection of claim 7 based on Wang is incorrect for at least this reason and should be withdrawn.

Claim 11 requires that the “second wiring layer includes a plurality of wirings, a predetermined wiring of said plurality of wirings is connected to said bonding pad, and an insulating film is provided for insulating said bonding pad from other wirings than the

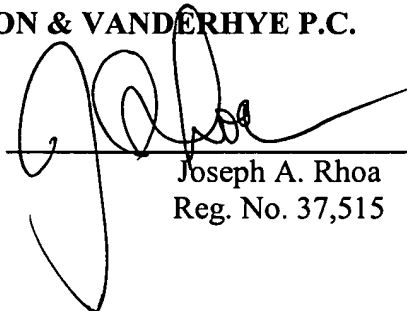
predetermined wiring among said plurality of wirings *so that a plurality of wirings of the second wiring layer which are located **directly under** the bonding pad are insulated from the bonding pad by the insulating film*, and wherein said insulating film is formed above said other wirings so as to directly contact the bonding pad.” Again, Wang fails to disclose or suggest these features of claim 11, and citation to APA cannot cure this fundamental flaw of Wang.

It is respectfully requested that all rejections be withdrawn. All claims are in condition for allowance. If any minor matter remains to be resolved, the Examiner is invited to telephone the undersigned with regard to the same.

Respectfully submitted,

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By: _____



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